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PATENTS R

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To the Director of the U.S. Patent and Trademark Office: Please record the attached original document or copy thereof.

1. Name of conveying party(ies):

- 1. Jianxiong LI;
- 2. Chi Chuen CHAW;
- 3. Ngai Kin TSUI;
- 4. Deming LIU;
- 5. Yiu Fai KWAN; and
- 6. Wai CHAN

Type of Entity: Individuals

Additional names(s) of conveying party(ies) attached? No

2. Name and Address of receiving party(ies):

ASM Assembly Automation Ltd.
 20/F., Watson Centre
 61-22 Kung Yip Street
 Kwai Chung
 Hong Kong, China SAR

Type of Entity: Corporation-Hong Kong

Additional name(s) & address(es) attached? No

3. Nature of Conveyance:

Assignment

Execution Date: December 20, 2004; December 24,
 2004; December 29, 2004; January
 5, 2005; January 18, 2005; January
 19, 2005.

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Application No.(s)

11/019,421

B. Patent No.(s)

Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:

OSTROLENK, FABER, GERB & SOFFEN, LLP
 1180 Avenue of the Americas
 New York, New York 10036-8403

6. Total number of documents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

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8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert C. Faber

Name of Person Signing

Robert C. Faber

Signature

February 14, 2005

Date

Total number of pages including cover sheet, attachments, and document: 2

WHEREAS, I (We), Jianxiong LI, Chi Chuen CHAW, Ngai Kin TSUI, Deming LIU, Yiu Fai KWAN and Wai CHAN as assignor(s), have invented certain improvements in COATING FOR ENHANCING ADHESION OF MOLDING COMPOUND TO SEMICONDUCTOR DEVICES for which an application for United States Letters Patent has been executed by me (us) of even date herewith; and

WHEREAS, ASM Assembly Automation Ltd, a corporation organized and existing under the laws of Hong Kong, China SAR and having a principal place of business at 20/F., Watson Centre, 16-22 Kung Yip St., Kwai Chung, Hong Kong, China SAR as assignee, is desirous of acquiring all right, title and interest in and to said invention and any Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I (We), as assignor(s), hereby sell, assign and set over to said assignee the entire right, title and interest for the United States and all other countries in and to said invention and the aforesaid application for Patent, all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States and all other countries, including all rights of priority from the filing of said application, and all rights for past infringement, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said inventions or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for myself (ourselves) and my (our) legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, reissue and other applications for Patent on said inventions and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said inventions, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to assist assignee, its successors, assigns and nominees to obtain patent protection for said invention in the United States and all other countries, the expenses incident to said applications to be borne and paid by said assignee.

Date: J. X. Lü Jan. 19/05 _____
Jianxiong LI

Date: 2004. 12. 24 _____
Chi Chuen CHAW

Date: 12.29.04 _____
Ngai Kin TSUI

Date: Dec 20/2004 _____
Deming LIU

Date: Jan 5/05 _____
Yiu Fai KWAN

Date: Jan 18/05 _____
Wai CHAN